

Maxence Bouvier, PhD

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AI & HW Research Scientist with 7+ years of experience in ML and Chip Design, currently leading innovations in ML for EDA at Huawei. Expertise spans ML for chip design and logic synthesis optimization, EDA automation, energy-efficient HW accelerators design, 2D/3D computer vision, transformer-based networks, large-scale workload distribution on multi-node servers.

EXPERIENCE

Huawei

AI & HW Research Scientist

Zurich, Switzerland

May 2024 - Present

- **Team Leader:** Built and led a multidisciplinary team of experts to develop innovative solutions for reducing switching activity and power consumption in Huawei's GPUs.
- **ML for Chip Design**
 - * Designed and developed an automated ML-based framework for iterative generation of multiplier circuits with reduced switching activity and lower power consumption. The full pipeline was up and running in less than three months, working alone.
 - * Deployed synthesis and simulation of millions of designs using containerized (Docker), open source EDA tools on a multi-node SLURM cluster. Adapted the framework for commercial EDA tools.
 - * Proved that Network Inversion is superior to other state of the art method for design generation (and design space exploration).
 - * Results: we found multiplier encodings that reduce power consumption by approximately 10% compared to conventional two's complement implementations. (*1 paper.*)
- **ML for Advanced Synthesis:** Developed a predictor-driven Logic Synthesis Optimization framework achieving up to 21% QoR improvement and 14 faster execution. - (*2 papers.*)
- **Characterization of ML Workloads Acceleration**
 - * Developed a simulation platform to accurately map (tiling and multi-core scheduling) tensor operations onto Huawei's Ascend "Cube" tensor accelerator.
 - * Exploited the simulator to benchmark tensor reshaping and vector reordering strategies, proposing novel software-level optimizations that effectively reduce power consumption.
- **Conference Attendance:** 2025 DAC, 2025 International Conference on LLM-Aided Design (ICLAD).

SONY

Senior AI Research Engineer

Zurich, Switzerland

Aug 2023 - Apr 2024

- **Sparsity Exploitation in Transformers**
 - * Engineered an asynchronous PointNet-based embedding, enabling continuous spatio-temporal data conversion into dense tensors for seamless, continuous feeding of Transformer models. - (*1 paper, 1 patent.*)
 - * Designed an NPU-compatible, block-wise sparse scaled dot-product attention module for highly efficient flash attention in Transformers, achieving more than 50% FLOPs reduction during inference and higher accuracy.
- **SLAM Enhanced AI Training:** Enhanced performance by incorporating a cutting-edge SLAM pipeline for multi-modal training process, achieving 6x faster model convergence and a 15% accuracy improvement.

AI Research Engineer

June 2022 - Aug 2023

- **SW/HW Co-Design Automation with Neural Architecture Search**
 - * Built an AI-driven, Hardware-Aware Neural Architecture Search framework. Reduced model FLOP cost to 8% of the original, with only a 4% accuracy loss.
 - * Integrated a Design Space Exploration software in the NAS loop to estimate energy and latency of model execution.
- **Transformer Hardware Acceleration Survey:** Conducted a literature study, featured in CTO's strategic report.
- **Vision Transformer for Image Generation**
 - * Implemented an AI model leveraging CNN and Transformer architectures to realize advanced frame generation. - (*1 patent.*)
 - * Built a live demo of the model, from image sensor to application. This led to 2 major collaborations with other teams.
 - * Packaged the model as an API to simplify sharing across teams and projects.
- **Software Maintainer:** Responsible for the CI of a few Python libraries shared among teams.
- **Conference Attendance:** 2023 ISSCC.

STMicroelectronics

Digital IC Design Engineer

Grenoble, France

Apr 2021 - May 2022

- **CPU Design and Automation**

- * Created a toolbox to automate component assembly of the Trace and Debug subsystem with ARM's Armv9-A SoC modules.
- * Developed an RTL generator for STM32 MPU SoC, streamlining the design of a multi-clock-domain reset and clock-control system for over 300 peripherals.

- **CPU Benchmarking:** Conducted CoreMark benchmarking on a multi-core MPU SoC, highlighting significant performance gains (up to 6x) through compiler updates.
- **Conference Attendance:** 2021 ISSCC.

CEA LETI

Doctoral Researcher on AI and Digital IC Design

Grenoble, France

Apr 2018 - Apr 2021

- **Neuromorphic Hardware Survey:** Conducted a comprehensive literature review on scalable, distributed, multi-chip neuromorphic hardware, leading to a widely cited publication in ACM JETC. - (1 paper.)
- **ULP NPU Design:** Built (RTL design, synthesis and layout) an ultra-low-power sparse AI accelerator, setting energy efficiency records (2.86pJ/OP in 28nm) and enabling seamless integration for 3D-stacked imagers. - (1 paper, 2 patents.)
- **EB VIO/SLAM Pipeline and Object Detection Innovation:** Developed an Event-Based VIO/SLAM pipeline with ego-motion compensation, leading to a solution for detecting moving objects. - (1 patent.)
- **Conference Attendance:** 2019 ISSCC, 2021 DAC.

IBM Research

Intern IC Design Engineer

Yorktown Heights, NY, USA

Feb 2017 - Aug 2017

- Automated wafer-scale memory device characterization, reducing execution time from days to hours.
- Contributed to the optimization of PCM technologies for Compute-in-Memory-based AI acceleration. - (1 paper, 1 patent.)

SKILLS

- **Languages:** Python, C/C++, SystemVerilog, MATLAB, VHDL
- **Libraries:** PyTorch, MLFlow, ONNX, CUDA, OpenCV, ROS, Dash, Flask, concurrent
- **Hardware & EDA Tools:** CocoTB, Yosys, OpenRoad, ABC, Mockturtle, Verilator, Design Compiler, QuestaSim, PrimeTime Power, PowerPro, Innovus
- **Software & DevOps:** Docker, Git, Continuous Integration (CI)

EDUCATION

- **Grenoble Alpes University | Ph.D. in Computer Science** Apr 2018 – Apr 2021 | Grenoble, France
- **EPFL | "M.Eng. in Electronics (Highest Honors)"** Sep 2015 – Sep 2017 | Lausanne, Switzerland
- **Grenoble Institute of Technology | B.Eng. in Electronics** Sep 2012 – Sep 2015 | Grenoble, France

PATENTS

- M. Bouvier, et al., “Apparatus, method, and computer program for processing visual event data,” *WO2024200170A1*, 2024.
- M. Bouvier, A. Valentian, “Observation system and associated observation method,” *US2023196779A1*, 2023.
- F. Carta, et al., “Pulsing synaptic devices based on phase-change memory to increase the linearity in weight update,” *US11557343B2*, 2023.
- M. Bouvier, A. Bige, “Device for compensating for movement of an event sensor, and associated systems and methods,” *WO2022117535A1*, 2022.
- M. Bouvier, A. Valentian, “Device for compensating movement of an event-driven sensor and associated observation system and method,” *US2022101006A1*, 2022.

PUBLICATIONS

- M. Bouvier, et al., “**GENIAL: Generative Design Space Exploration via Network Inversion for Low Power Algorithmic Logic Units,**” *Under Review*, 2025.
- F. Arnold, M. Bouvier, et al., “**Explicit Sign-Magnitude Encoders Enable Power-Efficient Multipliers,**” *International Workshop on Logic and Synthesis*, 2025.
- F. Arnold*, M. Bouvier*, et al., “**The Art of Beating the Odds with Predictor-Guided Random Design Space Exploration,**” *62nd ACM/IEEE Design Automation Conference (DAC) (Poster)*, 2025.
- C. M. Turrero, M. Bouvier, et al., “**ALERT-Transformer: Bridging Asynchronous and Synchronous Machine Learning for Real-Time Event-based Spatio-Temporal Data,**” *Proceedings of the 41st ICML*, 2024.
- M. Bouvier, et al., “**Scalable pitch-constrained neural processing unit for 3D integration with event-based imagers,**” *2021 58th ACM/IEEE Design Automation Conference (DAC)*, 2021.
- M. Bouvier, “**Study and design of an energy-efficient perception module combining event-based image sensors and spiking neural network with 3D integration technologies,**” *Ph.D. Dissertation, Université Grenoble Alpes*, 2021.
- M. Bouvier, et al., “**Spiking neural networks hardware implementations and challenges: A survey,**” *ACM Journal on Emerging Technologies in Computing Systems (JETC)*, 2019.
- P. Vivet, et al., “**Advanced 3D technologies and architectures for 3D smart image sensors,**” *2019 Design, Automation & Test in Europe Conference & Exhibition (DATE)*, 2019.